

FOR: BE SEMICONDUCTOR INDUSTRIES N.V.
Ratio 6
6921 RW Duiven
The Netherlands

PRESS RELEASE

BE Semiconductor Industries Announces Thin Film Solar Plating Orders

Duiven, the Netherlands, May 13, 2008, BE Semiconductor Industries N.V. ("the Company" or "Besi") (Euronext: BESI), a leading manufacturer of assembly equipment for the semiconductor industry, today announced the receipt of orders aggregating approximately € 3 million for thin film solar plating applications.

Besi's Mecco subsidiary received orders this week aggregating approximately € 3 million for plating lines to be utilized in thin film solar cell production. Such orders represent a follow-on purchase to a previously announced € 1.2 million in orders received in April 2008 for this application. The orders were placed by a European solar cell manufacturer and are expected to be delivered in the fourth quarter of 2008. Besi believes that Mecco's plating process is the most cost effective method in the marketplace today for the production of precursor material used in the manufacturing of thin film solar cells.

Richard Blickman, Chief Executive Officer of the Company, commented: "We are very pleased to receive these orders for thin film solar applications which represent in total approximately € 4.2 million to date in the second quarter of 2008 for this application. Such orders affirm Mecco's strategy to apply its leadership position in plating technology to other high growth market applications outside of the traditional semiconductor industry."

About BE Semiconductor Industries N.V.

BE Semiconductor Industries N.V. designs, develops, manufactures, markets and services die sorting, flip chip and multi-chip die bonding, packaging and plating equipment for the semiconductor industry's assembly operations. Its customers consist primarily of leading U.S., European and Asian semiconductor manufacturers, assembly subcontractors and electronics and industrial companies which utilize its products for both array connect and conventional leadframe manufacturing processes. For more information about Besi, please visit our website at www.besi.com.

Caution Concerning Forward Looking Statements

This press release contains forward-looking statements, which are found in various places throughout the press release, including statements relating to expectations of orders, net sales, product shipments, backlog, timing of purchases of assembly equipment by customers and capital expenditures. The words “anticipate”, “estimate”, “expect”, “can”, “intend”, “believes”, “may”, “plan”, “predict”, “project”, “forecast”, “will”, “would”, and similar expressions are intended to identify forward looking statements, although not all forward looking statements contain these identifying words. While these forward looking statements represent our judgments and future expectations concerning the development of our business, a number of risks, uncertainties and other important factors could cause actual developments and results to differ materially from our expectations. These factors include, but are not limited to, those listed or discussed in Besi’s Annual Report for the year ended December 31, 2006, as well as the risk that anticipated orders may not materialize or that orders received may be postponed or canceled, generally without charges; the volatility in the demand for semiconductors and our products and services; acts of terrorism and violence; overall global economic conditions; risks, such as changes in trade regulations, currency fluctuations, political instability and war, associated with substantial foreign customers, suppliers and foreign manufacturing operations; potential instability in foreign capital markets; the risk of failure to successfully manage our expanding and more diverse operations; and other key factors that could adversely affect our businesses and financial performance contained in our filings and reports, including our statutory consolidated statements. We are under no obligation to (and expressly disclaim any such obligation to) update or alter our forward-looking statements whether as a result of new information, future events or otherwise.

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PERSBERICHT

BE Semiconductor Industries kondigt orders aan voor plating lijnen voor "thin film" zonnecellen

Duiven, 13 mei 2008, BE Semiconductor Industries N.V. ("Besi") (Euronext: BESI), een toonaangevende leverancier van machines voor de assemblage van halfgeleiders heeft vandaag bekend gemaakt orders te hebben ontvangen voor een totaalbedrag van ongeveer € 3 mio bestaande uit plating lijnen voor "thin film" zonnecellen.

Besi dochter Meco heeft deze week orders ontvangen voor een totaalbedrag van ongeveer € 3 mio voor plating lijnen die gebruikt worden voor de productie van "thin film" zonnecellen. Deze orders zijn een vervolg op de eerder aangekondigde € 1,2 mio aan orders, ontvangen in april 2008, voor dezelfde toepassing. De orders zijn geplaatst door een Europese fabrikant van zonnecellen en verwacht wordt dat de orders in het vierde kwartaal van 2008 zullen worden geleverd. Besi is van mening dat Meco's plating technologie op dit moment de meest voordelige methode is voor de productie van "thin film" zonnecellen op basis van "precursor material".

Richard Blickman, Chief Executive Officer van Besi, lichtte toe: "Wij zijn uiterst content met in totaal ongeveer € 4,2 mio aan orders voor plating lijnen voor "thin film" zonnecellen toepassing. Deze orders bevestigen Meco's strategie om haar unieke plating technologie ook toe te passen in, naar verwachting, sterke groeiemarkten buiten de traditionele halfgeleiderindustrie".

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